

Page 17, line 15, change "photo optical quality material" to ~~A~~material that

a2 facilitates optical interconnection between semiconductor device 16 and an optical wave guide, another semiconductor device, or any source of an optical signal.*--.

line 15, change "billed" to --filled--.

Page 18, line 1, change "Ti/CuT" to --Ti/Cu/Ti--.

Page 19, line 7, change "metal 18" to --thin film overlay 18--.

In the claims:

Amend claim 1 as follows:

1. (Amended) A device comprising:

a package having a cavity therein;

a semiconductor device in said cavity, said semiconductor device having at least one optical receiver and/or transmitter adjacent a surface of said semiconductor device facing away from said package; and

a thin overlay electrically connecting bond pads on said semiconductor device to electrically conductive pads on a layer of said thin film overlay facing away from said semiconductor device.

Amend claim 3 as follows:

a4 3. (Amended) The device of Claim 2, in which the dimensions of said [package includes a] cavity [that] match[es] or exceed[s] the dimensions of the semiconductor device.

Cancel claims 26 to 44.